

IN THE CLAIMS

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A thermal head, comprising:

a substrate;

a thermal storage layer disposed on one main surface of the substrate so as to extend to an edge of the substrate, the thermal storage layer being formed of glass;

electrodes disposed on or above the thermal storage layer apart from the edge of the substrate;

heat-generating resistors disposed above the thermal storage layer apart from the edge of the substrate, the heat-generating resistors being connected to the electrodes; and

a first covering layer disposed on or above the electrodes and the heat-generating resistors; ~~and~~

~~—— a protection film disposed on or above the first covering layer,~~

the first covering layer extending from atop the electrodes and the heat-generating resistors toward atop the thermal storage layer on the edge of the substrate, ~~the~~ a protection film being disposed on or above the first covering layer

disposed on or above the electrodes and the heat-generating resistors and an edge of the protection film being not disposed above the edge of the substrate.

2. (Original) The thermal head according to claim 1,

wherein the edge of the protection film is positioned between the electrodes and the heat-generating resistors, and the edge of the substrate.

3. (Currently Amended) The thermal head according to claim 1 ~~or 2~~,

wherein the first coverage layer has a higher Vickers hardness than that of the thermal storage layer.

4. (Currently Amended) The thermal head according to claim 1 ~~any one of claims 1 to 3~~,

wherein the protection film has a lower Vickers hardness than that of the thermal storage layer.

5. (Currently Amended) The thermal head according to claim 1 ~~any one of claims 1 to 4~~, comprising:

a second covering layer disposed between the first covering layer and the protection film.

6. (Currently Amended) The thermal head according to claim 1 ~~any one of claims 1 to 5~~,

wherein the first covering layer is made of SiN.

7. (Currently Amended) The thermal head according to claim 5 ~~or 6~~,

wherein the second covering layer is made of SiON.

8. (Currently Amended) The thermal head according to claim 5 ~~or 6~~,

wherein the second covering layer is made of SiO₂.

9. (Currently Amended) The thermal head according to claim 1 ~~any one of claims 1 to 8~~, comprising:

a resin layer disposed above a region extending from the edge of the substrate to the protection film,

a portion of the resin layer positioned above the edge of the substrate being disposed higher than a portion of the resin layer positioned above the protection film.

10. (Currently Amended) A thermal printer, comprising:

the thermal head according to claim 1 ~~any one of claims 1 to 9~~;

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a conveyance mechanism that conveys a recording medium on a plurality of heat-generating portions; and

a platen roller that presses the recording medium on the plurality of heat-generating portions.